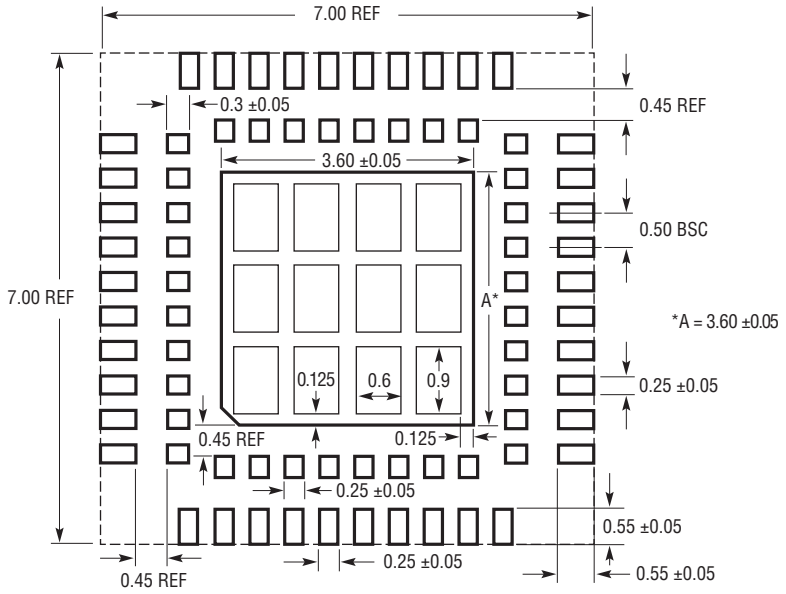
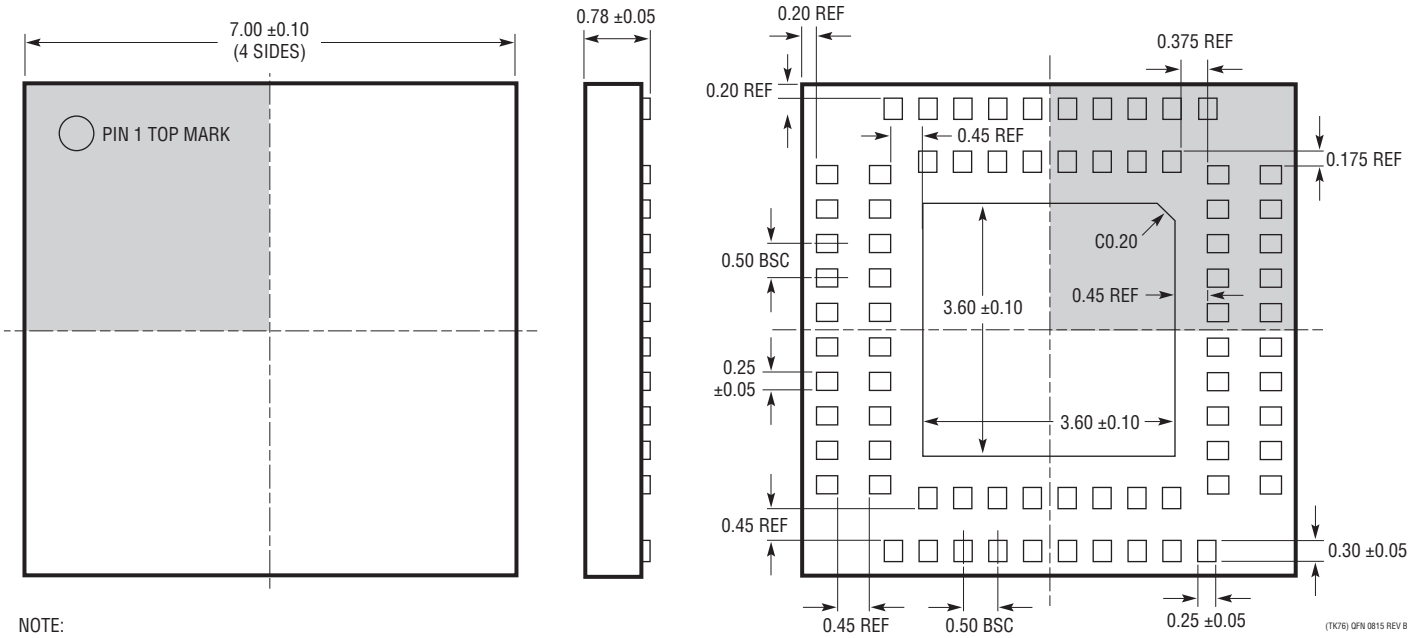
TK Package
76-Lead Plastic TLA QFN (7mm × 7mm)
(Reference LTC DWG # 05-08-1989 Rev B)



RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



BOTTOM VIEW—EXPOSED PAD

NOTE:
1. DRAWING NOT TO SCALE
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE, IF PRESENT
4. EXPOSED PAD SHALL BE SOLDER PLATED
5. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
6. 4 MIL THICK LASER CUT STENCIL IS RECOMMENDED. STENCIL OPENING 1:1 TO PCB LAND PATTERN.